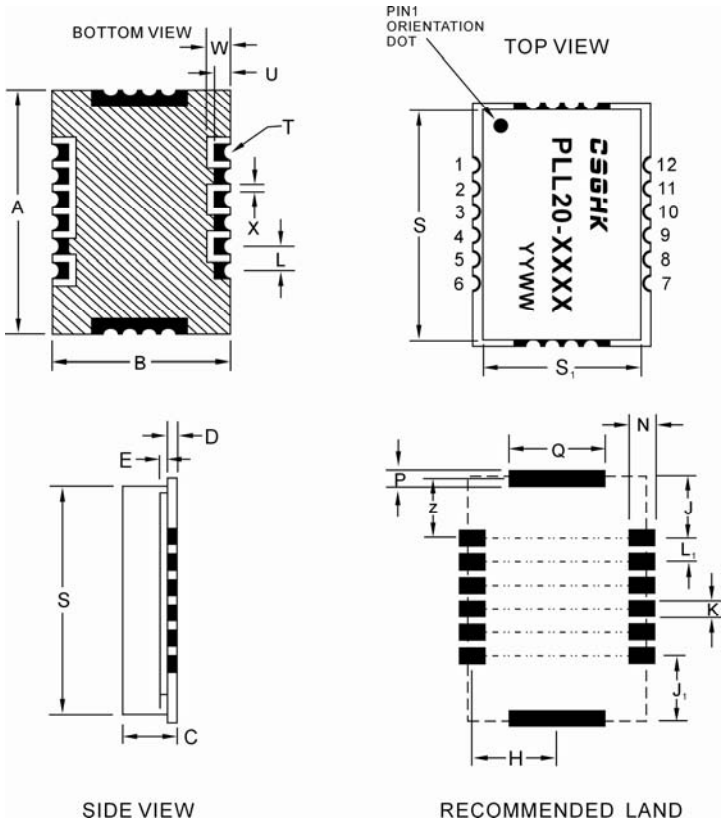
REVISIONS

NOTE，UNLESS OTHERWISE SPECIF IED：

1. THE METAL CASE IS GROUND
2. ALL HALF VIA CONTACTS ARE PLATED THRU FOROM THE PAD ON THE TOP SIDE TO THE PAD ON THE BOTTOM SIDE OF THE BOARD.
3. HATCHED AREAS GROUND AND ARE COVERED WINTH LPI SOLDER MASK OVER BARE COPPER. ALL CONTACT AREAS ARE PLATED. SIGNAL VIAS MAY BE LOCATED WITHIN GROUND PLANE.
4. SUBSTRATE MATERIAL：FR-4
5. XXXX PEPRFSENTS THE MODEL NUMBER.
6. YYWW IS THE DATA CODE.

PIN OUT FOR PLL	
PIN	APPLICATION
1	VCC（CHIP）
3	OSC IN
5	VCC（VCO）
7	RF OUT
9	LOCK DETECT
10	CLOCK
11	DATA
12	ENABLE

ALL OTHER PINS ARE GROUND



SYMBOL	DIMENSION	
	MILLIMETERS	INCHES
A	20.3±0.25	0.800±0.010
B	14.8±0.25	0.582±0.010
C	3.50	0.138
D	0.99MAX	0.039MAX
E	0.51	0.020
H	6.91	0.272
J	5.16	0.203
J_1	5.13	0.202
K	1.50	0.059
L	2.00±0.05	0.080±0.002
L_1	2.00	0.080
N	1.98	0.078±0.003
P	1.52	0.060±0.003
Q	7.40	0.291±0.003
S	19.56	0.770
S_1	14.02	0.552
T	R=0.50	R=0.020
U	1.47	0.058
W	1.78	0.070
X	0.51	0.020
Z	4.90	0.193

	APPROVALS	DATA	CSGHK
DRAWN BY			
CHECKED BY			PLL-20 PACKAGE MECHANICAL PCB OUTLINE
PROCESS ENG			
QUALITY			